

PRESS RELEASE

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For Immediate Release

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Another Key Patent Issued

Beam Shaping with Azimuthally - Varying Aberrations

SANTA CLARA, CA - October 15, 2012 - Multibeam Corporation announced the addition of another key patent to its portfolio. The U.S. Patent and Trademark Office has granted US Patent # 8,242,457 B2 to Multibeam Corporation. This invention relates to the field of charged particle optics, and in particular to systems for generating high current density shaped electron beam. This patent, together with other Multibeam's IP, is the foundation for many critical applications in lithography and inspection in the field of microchip production.

Multibeam's key invention is a unique electron-beam technology that eliminates the magnetic field in the column. This enables the columns to be small in footprint and fast in deflection. When multiple columns, properly designed for the target application, are assembled in an array, the architecture is capable of meeting the needs for high-volume manufacturing as well as low-volume production and device prototyping. Multibeam's multi-column approach overcomes e-beam's well-known deficiency in low speed while taking advantage of its high resolution, unleashing a multitude of applications that are impossible with today's technology.

Multibeam has 18 patents granted in the United States, as well as a pipeline of patents pending. In addition to Multibeam's patent portfolio, the company has completed substantial research, development, and engineering in e-beam columns and column-array architecture for patterning microchips and inspecting defects on wafer.

About Multibeam Corporation

Headquartered in Santa Clara, California, Multibeam Corporation is a leading developer of multi-column e-beam technologies that add high value to semiconductor lithography by doing away with costly masks. The company's Complementary E-Beam Lithography (CEBL) system augments optical lithography at critical layers by eliminating expensive optical multiple patterning at 20nm processing nodes and beyond. Multibeam's systems can also be cost-efficiently leveraged as primary lithographic tools for low-volume production of ASICs as well as in multi-project wafer programs. Multibeam's patent-protected e-beam technologies encompass deployment of multi-column arrays to perform wafer inspection.

For more information, visit www.multibeamcorp.com.